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REMARKS

Thorough examination and careful review of the application by the Examiner is noted and appreciated.

The gracious allowance of claims 11, 12 and 15 is further acknowledged and appreciated.

Claims 1, 4, 8-12 and 15-20 are pending in the application. Claims 1, 4 and 8-10 stand rejected.

Claim Rejections Under 35 USC 112

Claims 1, 4 and 8-10 are rejected under 35 USC 112, first paragraph, as failing to comply with the written description requirement. The Examiner contended that "the specification does not provide process steps of how it is possible that plasma curing could happen as a result of a subsequent process step (utilizing electron beam)".

Claims 1, 4 and 8-10 are rejected under 35 USC 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention. The same objection was raised by the Examiner.

Independent claim 1 has been amended to correct a typographical error in which the words "substantially prevent" were omitted when claim 1 was amended. This change is supported by the original claim 1, last paragraph (now deleted), which states "such that plasma treating the semiconductor wafer prior to measuring the one or more critical dimensions using the electron beam substantially prevents shrinkage of the at least one photoresist layer when

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using the electron beam". The present invention independent claim 1, after the correction of the typographical error, reads:

"Claim 1. A method comprising:  
plasma curing at least one photoresist layer of a semiconductor wafer  
**to substantially prevent** shrinkage resulting from subsequently  
utilizing an electron beam for critical dimension measurement; and,  
measuring one or more critical dimensions on the at least one  
photoresist layer using the electron beam."

The rejection of claims 1, 4 and 8-10 under 35 USC 112, first paragraph and second paragraph, is therefore respectfully traversed. A reconsideration for allowance of these claims is respectfully requested of the Examiner.

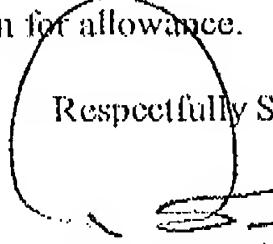
Based on the foregoing, the Applicants respectfully submit that all of the pending claims, i.e. claims 1, 4 and 8-10, are now in condition for allowance. Such favorable consideration by the Examiner at an early date is respectfully requested.

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In the event that the present invention is not in a condition for allowance for any other reasons, the Examiner is respectfully invited to call the Applicants' representative at his Bloomfield Hills, Michigan office at (248) 540-4040 such that necessary action may be taken to place the application in a condition for allowance.

Respectfully Submitted,

  
Randy Tung (31,311)